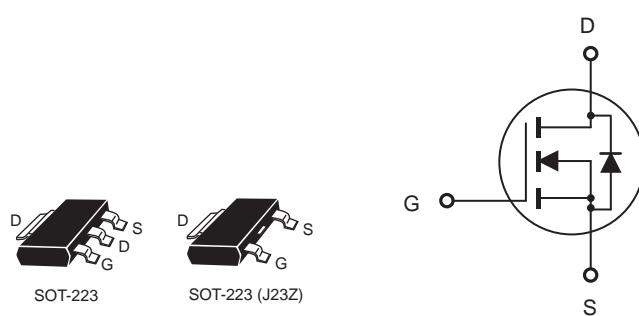


## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

- 60V, 4.0A,  $R_{DS(ON)} = 100m\Omega$  @  $V_{GS} = 10V$ .
- High dense cell design for extremely low  $R_{DS(ON)}$ .
- Rugged and reliable.
- Lead free product is acquired.
- SOT-223 package.



### ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	4.0	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	25	A
Maximum Power Dissipation	$P_D$	3	W
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient <sup>b</sup>	$R_{\theta JA}$	42	$^\circ C/W$



# CET3055

## Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 48\text{V}, V_{\text{GS}} = 0\text{V}$			10	$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
<b>On Characteristics<sup>c</sup></b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2		4	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 4\text{A}$		75	100	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}} = 15\text{V}, I_D = 4\text{A}$	3	4		S
<b>Dynamic Characteristics<sup>d</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		335		pF
Output Capacitance	$C_{\text{oss}}$			150		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			40		pF
<b>Switching Characteristics<sup>d</sup></b>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 25\text{V}, I_D = 1.2\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 50\Omega$		17	25	ns
Turn-On Rise Time	$t_r$			24	50	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			41	65	ns
Turn-On Fall Time	$t_f$			33	60	ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 48\text{V}, I_D = 4\text{A}, V_{\text{GS}} = 10\text{V}$		10	13	nC
Gate-Source Charge	$Q_{\text{gs}}$			2.4		nC
Gate-Drain Charge	$Q_{\text{gd}}$			4.0		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current <sup>b</sup>	$I_S$				2.5	A
Drain-Source Diode Forward Voltage <sup>c</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 4\text{A}$			1.2	V

Notes :

a.Repetitive Rating : Pulse width limited by maximum junction temperature.

b.Surface Mounted on FR4 Board,  $t \leq 10$  sec.

c.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

d.Guaranteed by design, not subject to production testing.

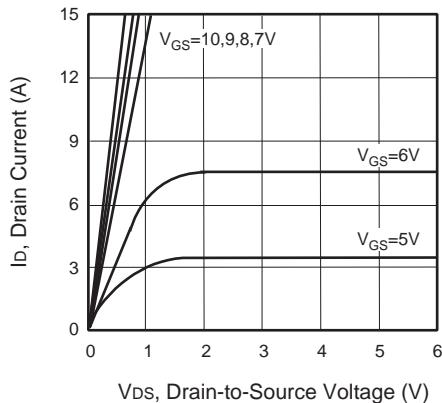


Figure 1. Output Characteristics

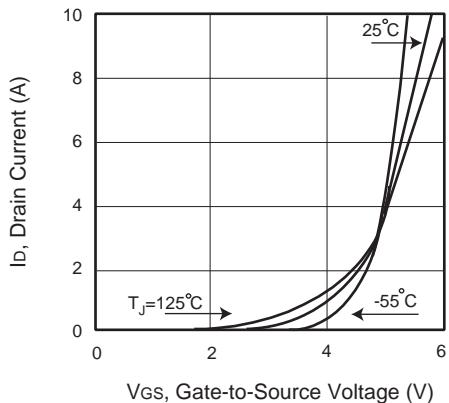


Figure 2. Transfer Characteristics

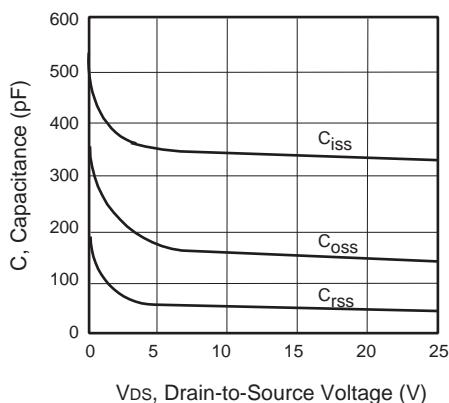


Figure 3. Capacitance

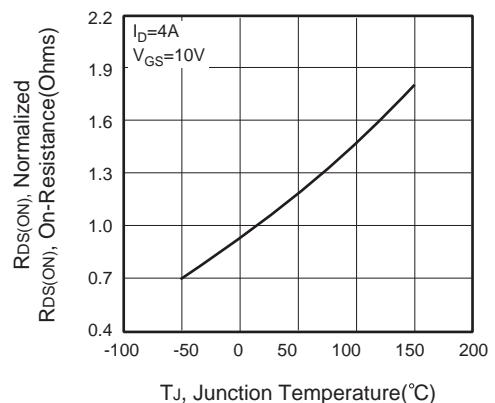


Figure 4. On-Resistance Variation with Temperature

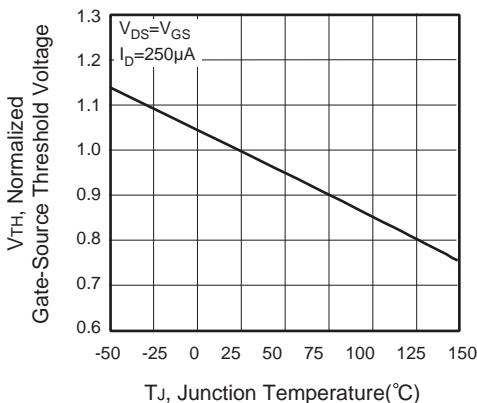


Figure 5. Gate Threshold Variation with Temperature

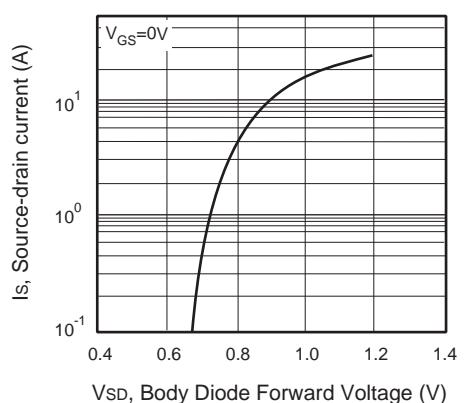
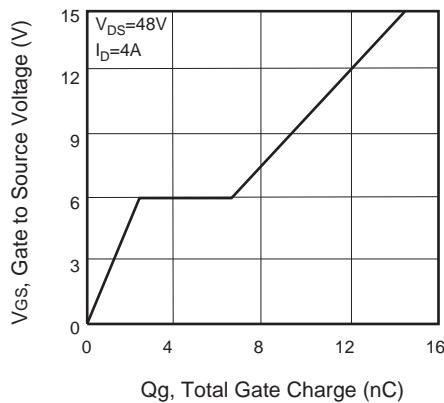
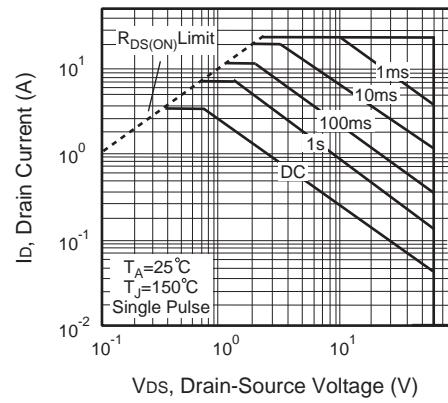


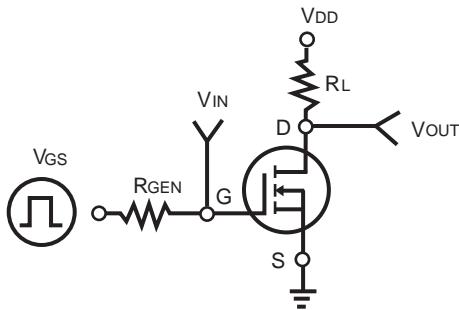
Figure 6. Body Diode Forward Voltage Variation with Source Current



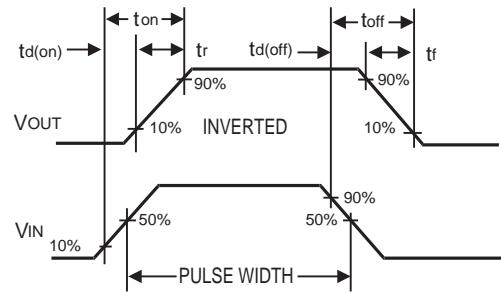
**Figure 7. Gate Charge**



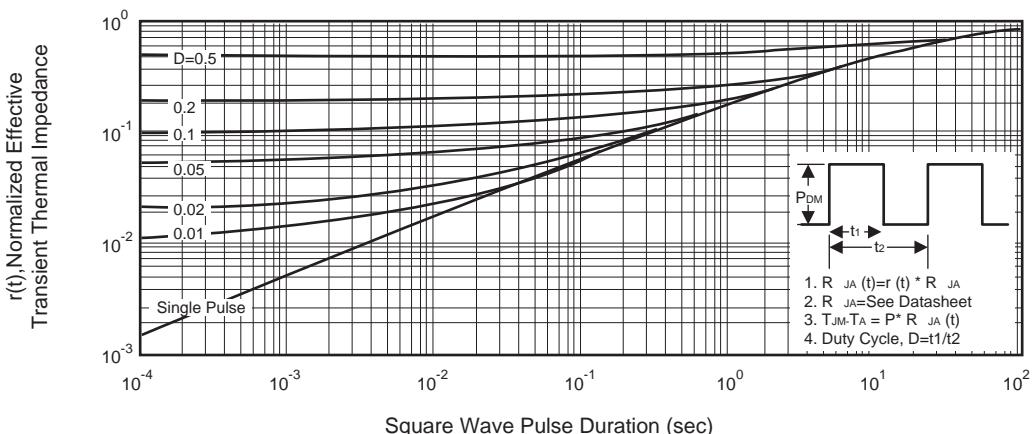
**Figure 8. Maximum Safe Operating Area**



**Figure 9. Switching Test Circuit**



**Figure 10. Switching Waveforms**



**Figure 11. Normalized Thermal Transient Impedance Curve**